



STTH2003CT/CG/CF

HIGH FREQUENCY SECONDARY RECTIFIER

MAJOR PRODUCT CHARACTERISTICS

$I_{F(AV)}$	2 x 10 A
V_{RRM}	300 V
$T_j(\text{max})$	175 °C
$V_F(\text{max})$	1 V
$t_{rr}(\text{max})$	35 ns

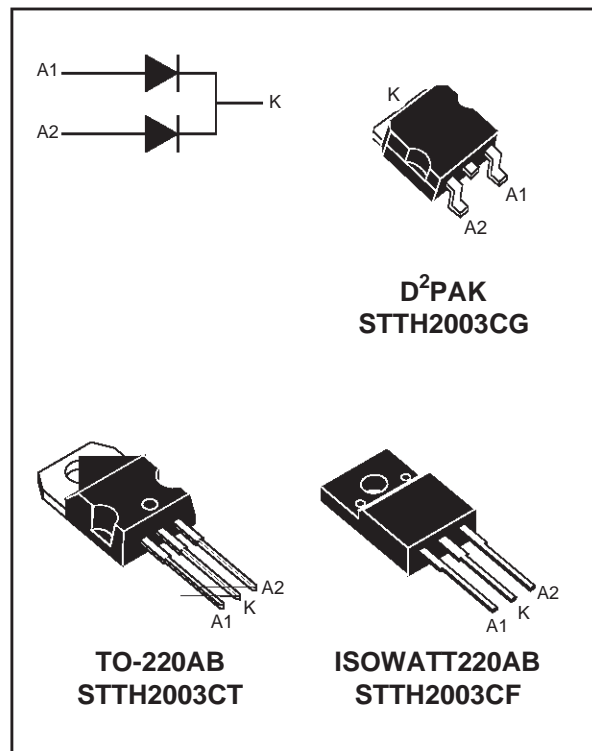
FEATURES AND BENEFITS

- COMBINES HIGHEST RECOVERY AND REVERSE VOLTAGE PERFORMANCE
- ULTRAFAST, SOFT AND NOISE-FREE RECOVERY FOR LOW SIDE EFFECTS

DESCRIPTION

Dual center tap Fast Recovery Epitaxial Diodes suited for Switch Mode Power Supply and high frequency DC/DC converters.

Packaged in TO-220AB or D²PAK this device is especially intended for secondary rectification.



ABSOLUTE RATINGS (limiting values, per diode)

Symbol	Parameter			Value	Unit	
V_{RRM}	Repetitive peak reverse voltage			300	V	
$I_{F(RMS)}$	RMS forward current			30	A	
$I_{F(AV)}$	Average forward current $\delta = 0.5$	TO-220AB / D ² PAK	$T_c = 140^\circ\text{C}$	Per diode	10	A
		ISOWATT220AB	$T_c = 105^\circ\text{C}$	Per device	20	
I_{FSM}	Surge non repetitive forward current		$t_p = 10 \text{ ms}$ sinusoidal	110	A	
I_{RSM}	Non repetitive avalanche current		$t_p = 20 \mu\text{s}$ square	5	A	
T_{stg}	Storage temperature range			-65 + 175	°C	
T_j	Maximum operating junction temperature			175	°C	

THERMAL RESISTANCES

Symbol	Parameter			Value	Unit
R _{th(j-c)}	Junction to case	TO-220AB/ D ² PAK	Per diode	2.5	°C/W
			Total	1.3	
		ISOWATT220AB	Per diode	3.2	
			Total	3.9	
R _{th(c)}		TO-220AB/ D ² PAK	Coupling	0.1	
		ISOWATT220AB	Coupling	2.5	

STATIC ELECTRICAL CHARACTERISTICS (per diode)

Symbol	Parameter	Tests conditions		Min.	Typ.	Max.	Unit
I _R *	Reverse leakage current	V _R = 300 V	T _j = 25°C			20	μA
			T _j = 125°C		30	300	
V _F **	Forward voltage drop	I _F = 10 A	T _j = 25°C			1.25	V
		I _F = 10 A	T _j = 125°C		0.85	1	

Pulse test: * t_p = 5 ms, δ < 2 %

** t_p = 380 μs, δ < 2%

To evaluate the maximum conduction losses use the following equation:

$$P = 0.75 \times I_{F(AV)} + 0.025 I_{F(RMS)}^2$$

RECOVERY CHARACTERISTICS

Symbol	Tests conditions			Min.	Typ.	Max.	Unit
t _{rr}	I _F = 0.5 A	I _{rr} = 0.25 A	I _R = 1 A	T _j = 25°C		25	ns
	I _F = 1 A	dI _F /dt = - 50 A/μs	V _R = 30 V			T _j = 25°C	
t _{fr}	I _F = 10 A	dI _F /dt = 100 A/μs	V _{FR} = 1.1 x V _F max.	T _j = 25°C		230	ns
V _{FP}				T _j = 25°C		3.5	V
S _{factor}	V _{CC} = 200V	I _F = 10 A	dI _F /dt = 200 A/μs	T _j = 125°C	0.3		-
I _{RM}							8

Fig. 1: Conduction losses versus average current (per diode).

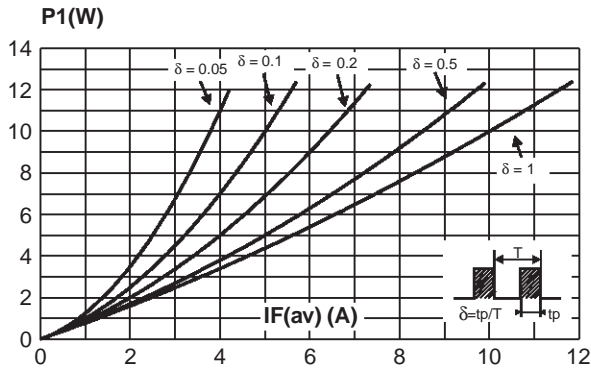


Fig. 2: Forward voltage drop versus forward current (maximum values, per diode).

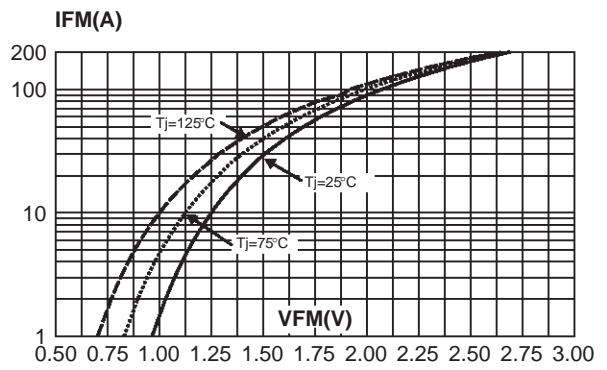


Fig. 3-1: Relative variation of thermal impedance junction to case versus pulse duration (TO-220AB / D²PAK).

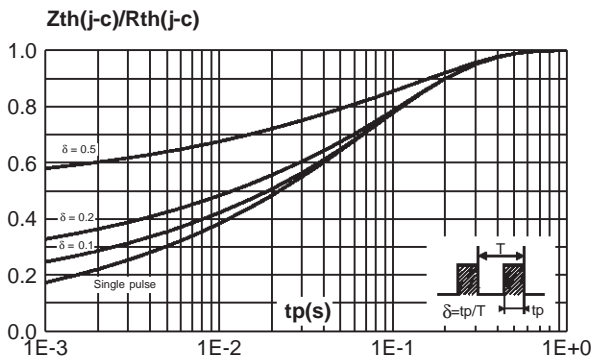


Fig. 3-2: Relative variation of thermal impedance junction to case versus pulse duration (ISOWATT220AB).

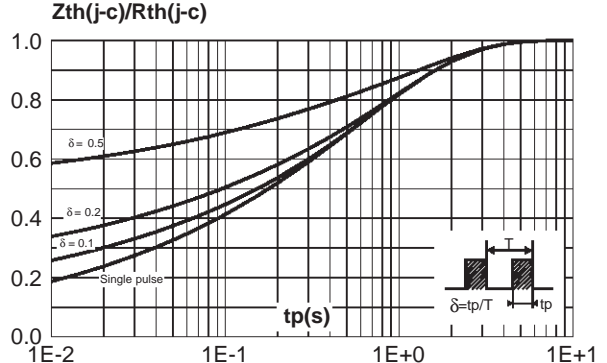


Fig. 4: Peak reverse recovery current versus dIF/dt (90% confidence, per diode).

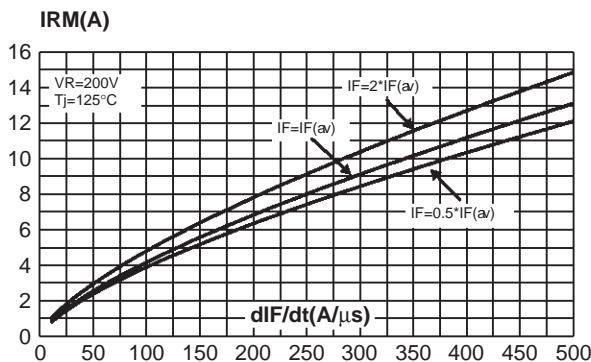


Fig. 5: Reverse recovery time versus dIF/dt (90% confidence, per diode).

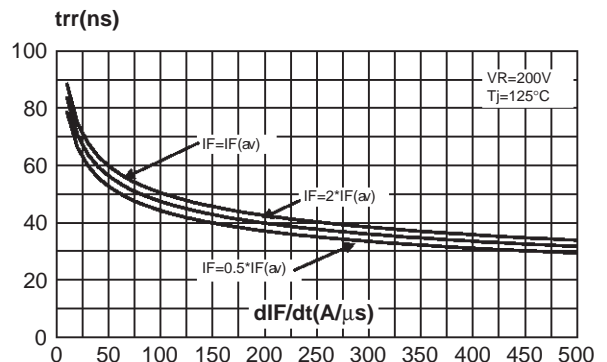


Fig. 6: Softness factor (t_b/t_a) versus dI/dt (typical values, per diode).

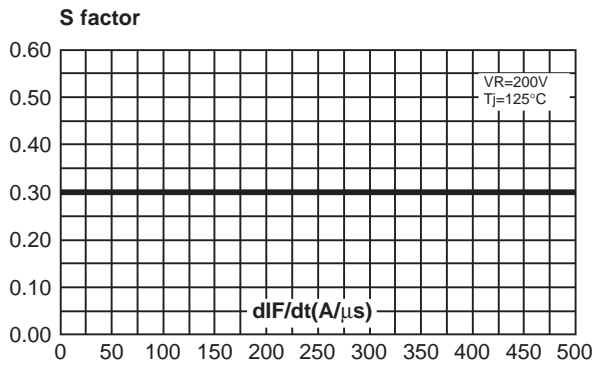


Fig. 7: Relative variation of dynamic parameters versus junction temperature (reference: $T_j = 125^\circ C$).

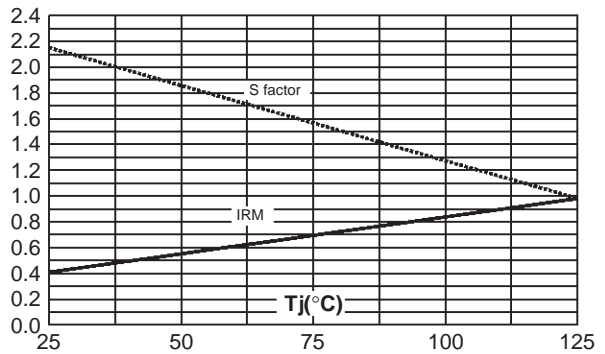


Fig. 8: Transient peak forward voltage versus dI/dt (90% confidence, per diode) (TO-220AB).

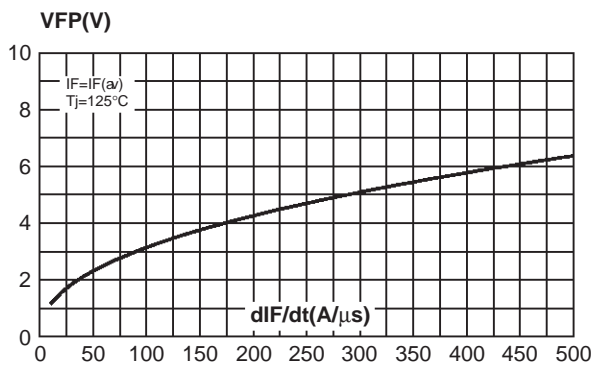


Fig. 9: Forward recovery time versus dI/dt (90% confidence, per diode).

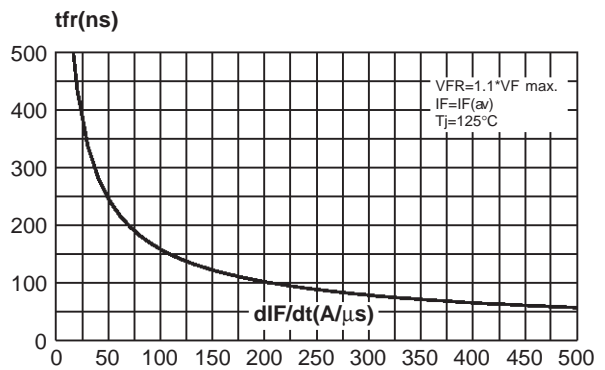
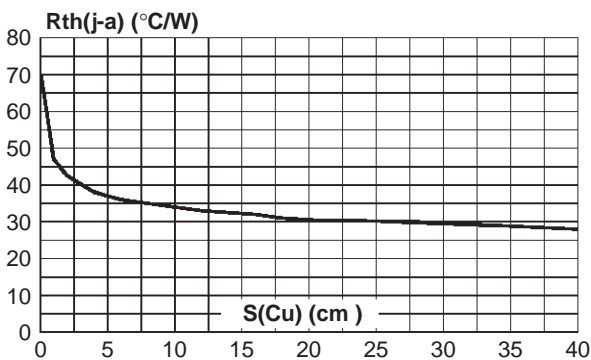
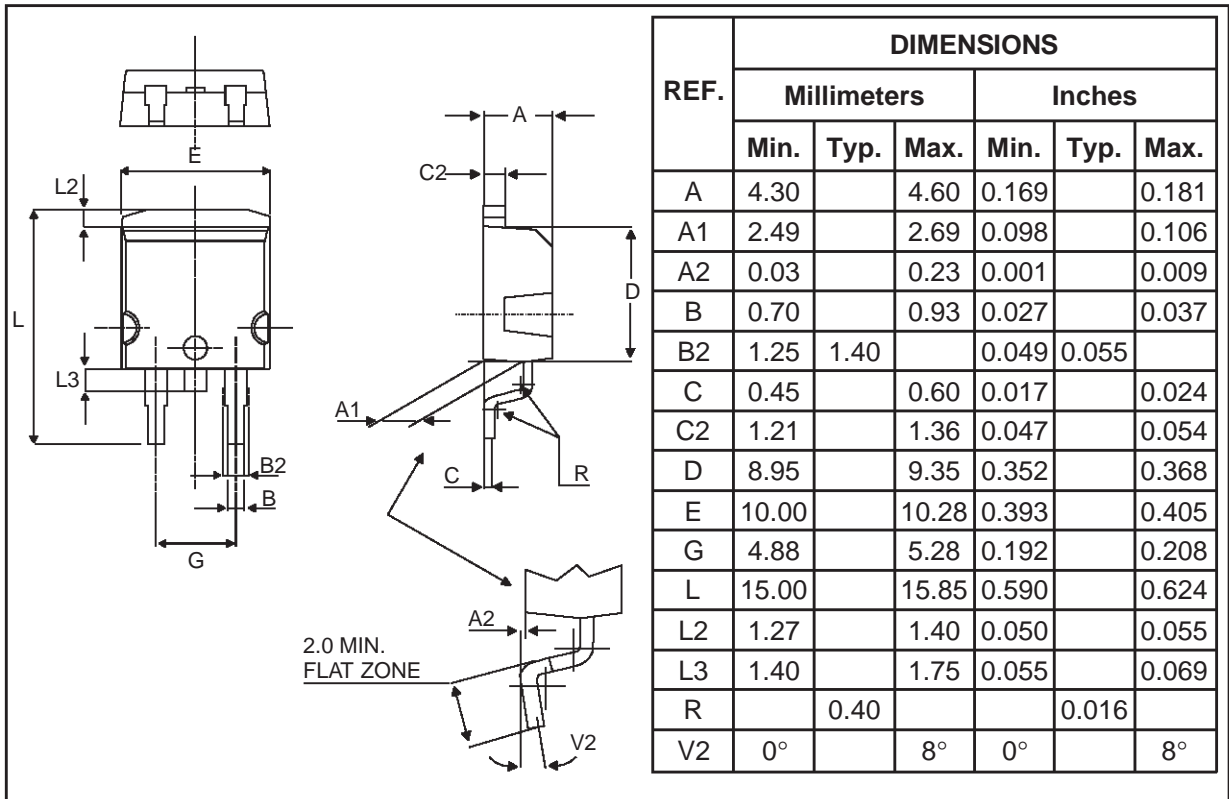


Fig. 10: Thermal resistance junction to ambient versus copper surface under tab (Epoxy printed circuit board FR4, copper thickness: $35\mu m$) (D^2PAK)

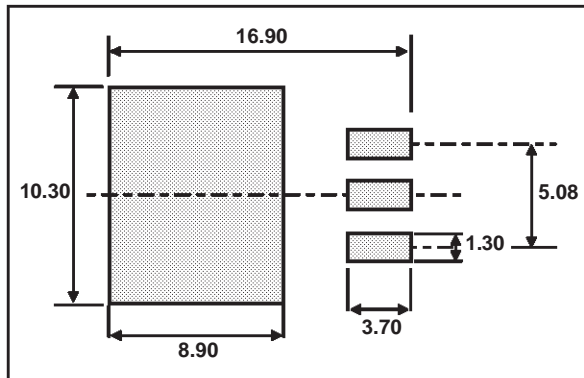


PACKAGE MECHANICAL DATA
D²PAK

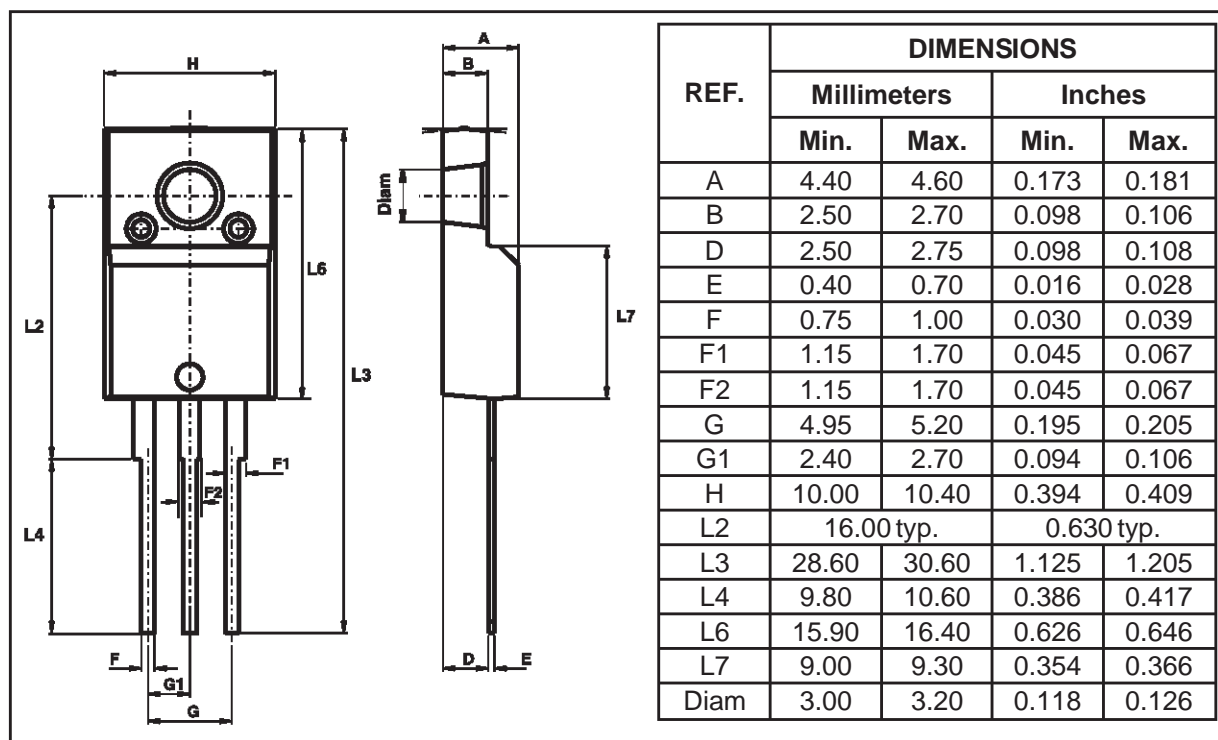


FOOT PRINT DIMENSIONS (in millimeters)
D²PAK

■ Cooling method : by conduction (method C)

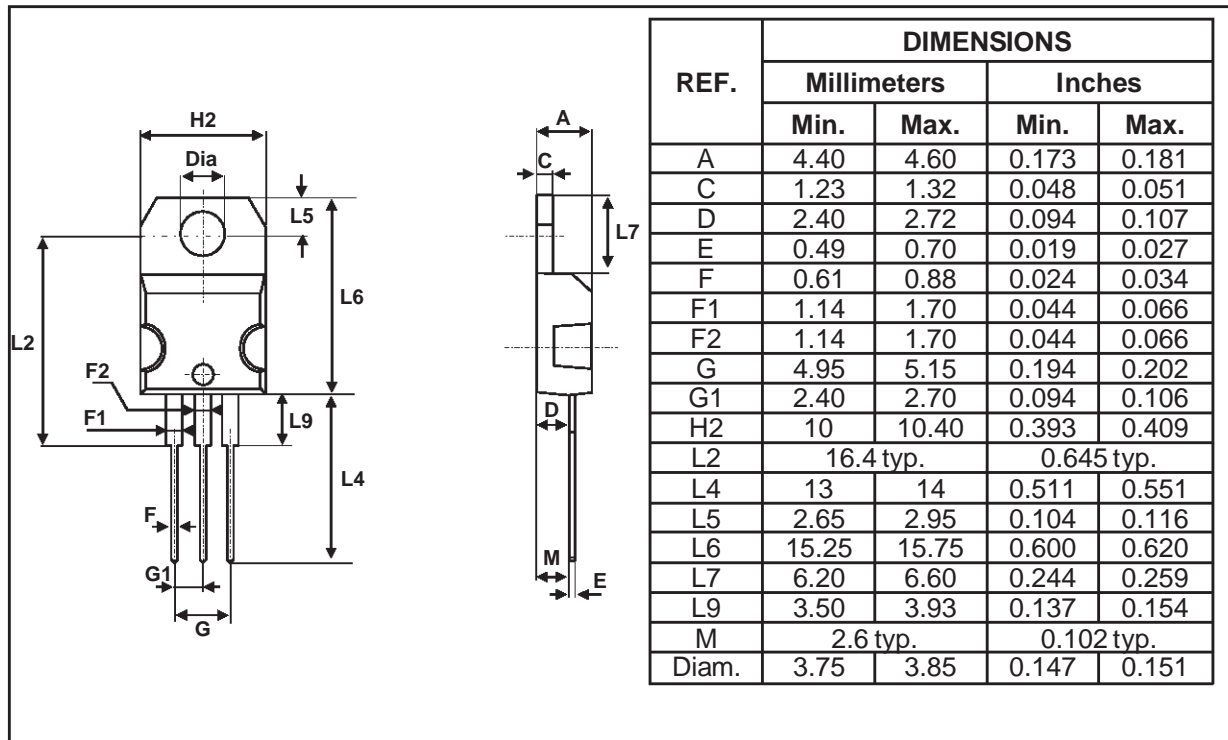


PACKAGE MECHANICAL DATA
ISOWATT220AB



- Cooling method : C
- Recommended torque value : 0.55 m.N
- Maximum torque value : 0.70 m.N

PACKAGE MECHANICAL DATA
TO-220AB



- Cooling method : by conduction (C)
- Recommended torque value : 0.55 m.N
- Maximum torque value : 0.70 m.N

Ordering code	Marking	Package	Weight	Base qty	Delivery mode
STTH2003CT	STTH2003CT	TO-220AB	2.2g	50	Tube
STTH2003CG	STTH2003CG	D ² PAK	1.48g	50	Tube
STTH2003CF	STTH2003CF	ISOWATT220AB	2.08g	50	Tube

- Epoxy meets UL 94,V0

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